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(54) **LABEL FOR IN-MOLD FORMING**

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(58) **Field of Classification Search**

None

See application file for complete search history.

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(57) **ABSTRACT**

A label for in-mold forming comprising a thermoplastic resin film with a heat-sealable layer, a printable thermoplastic resin film, and an antenna and an IC chip. The antenna and the IC chip are interposed between the thermoplastic resin films. The label is strong and water resistant with a high adhesive strength. The label has the function of an IC label and has a printable surface. Also provided is a thermoplastic resin container bearing the label. Bonding the label to a thermoplastic resin container does not damage the IC chip and antenna.

26 Claims, No Drawings